

ABSTRACT OF THE DISCLOSURE

A multi-chips module package comprises a main substrate, a first chip, a second chip, a die-substrate, a plurality of electrically conductive wires and an encapsulation. The first chip and the second chip are respectively electrically connected to the main substrate via the electrically conductive wires, and the first chip is electrically connected to the second chip through the die-substrate. In such a manner, the thickness of the multi-chips module package will be reduced and the path of the electrical signal transmission will be shortened to enhance electrical performance.